

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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SMD0805

SMD Type, 6 V / 9 V / 15V

Standard

UL 1434 1st Edition

CSA C22.2 No. 0 CSA TIL No. CA-3A

Approvals

cULus Recognition

ΤÜV

Features

These devices offer wide range in hold currents from 0.1 A to 1.0 A and voltages from 6 V to 15 V. The SMD0805 product line is suitable for high density circuit board applications in computers, cellular phone and general electronics. Suitable for reflow soldering.

Specifications

Packaging

Blistertape and reel Ø 178 mm

Materials

Terminals: Solder-plated copper

TS: Solder Material: 63/37 SnPb

TF: Solder Material: Sn

Max. Device Surface Temperature in Tripped State

125 °C

Operating / Storage Temperature

-40 °C to +85 °C (consider derating)

Humidity Ageing

+85 °C, 85 % R.H., 1000 hours, ± 5 % typical

resistance change

Vibration

MIL-STD-883C, Method 2007.1, Condition A, no change

Thermal Shock

MIL-STD-202F, Method 107G

+85 °C to -40 °C 20 times, -30 % typical resistance

Solderability

Meets EIA Specification RS186-9E, ANSI/J-STD-002, Category 3

Reflow only

Solvent Resistance

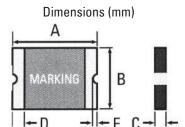
MIL-STD-202, Method 215, no change

Marking

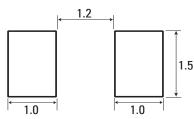
"P", Part Code







Solder pad Layout (mm)



Dimensions (mm)										Tov Allemand
Model	А			В		С	D		E	packaging quantity
	Min	Max	Min	Max	Min	Max	Min	Min	Max	tape
SMD0805P010TS/ <i>TF</i>	2.00	2.20	1.20	1.50	0.55	1.00	0.10	0.20	0.45	4,000
SMD0805P020TS/ <i>TF</i>	2.00	2.20	1.20	1.50	0.55	1.00	0.10	0.20	0.45	4,000
SMD0805P035TS/ <i>TF</i>	2.00	2.20	1.20	1.50	0.45	0.75	0.10	0.20	0.45	4,000
SMD0805P050TS/ <i>TF</i>	2.00	2.20	1.20	1.50	0.75	1.25	0.10	0.20	0.45	3,000
SMD0805P075TS/ <i>TF</i>	2.00	2.20	1.20	1.50	0.75	1.25	0.20	0.15	0.45	3,000
SMD0805P100TS/ <i>TF</i>	2.00	2.20	1.20	1.50	0.80	1.80	0.20	0.15	0.45	2,000

Model	l _{hold} I _{Trip}		V _{max. dc}	l _{max.}	max. time to trip	P _{d max.}	Resistance			Approvals
	(A)	(Å)	(V)	(A)	(sec. @ A)	(VV)	$R_{min.}(\Omega)$	$R_{typ.}(\Omega)$	$R_{I \text{ max.}}(\Omega)$	cURus TÜV
SMD0805P010TS/ <i>TF</i>	0.10	0.30	15	40	1.50 @ 0.50	0.5	1.000	3.500	6.000	
SMD0805P020TS/ <i>TF</i>	0.20	0.50	9	40	0.02 @ 8.00	0.5	0.650	2.000	3.500	
SMD0805P035TS/ <i>TF</i>	0.35	0.75	6	40	0.10 @ 8.00	0.5	0.250	0.750	1.200	
SMD0805P050TS/ <i>TF</i>	0.50	1.00	6	40	0.10 @ 8.00	0.5	0.150	0.500	0.850	
SMD0805P075TS/ <i>TF</i>	0.75	1.50	6	40	0.20 @ 8.00	0.6	0.090	0.260	0.350	рр
SMD0805P100TS/ <i>TF</i>	1.00	1.95	6	40	0.30 @ 8.00	0.6	0.060	0.120	0.210	рр

Please choose TS for SnPb and TF for Sn plating

NOTE:

Hold current; maximum current device will pass without tripping in 20 °C still air.

Trip current: minimum current at which the device will trip in 20 °C still air. Maximum voltage device can withstand without damage at rated current (I Maximum fault current device can withstand without damage at rated voltage (V_{max}) Power dissipated from device when in the tripped state at 20 °C still air.

Minimum resistance of device in initial (un-soldered) state.

Maximum resistance of device at 20 °C measured one hour after tripping for 20 s.

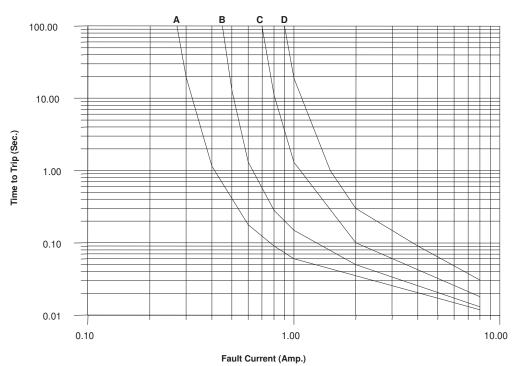
Camation: Operation beyond the specified rating may result in damage and possible arcing and flame. Specifications are subject to change without notice

Order Information

Ωty.	Order-	Model	Packaging		
	Number				







- A: SMD0805P010TS/TF
- B: SMD0805P020TS/TF
- C: SMD0805P035TS/TF
- D: SMD0805P050TS/TF

Thermal Derating Chart

Model	Ambient Operation Temperature - I _{hold} (A)								
	-40 °C	-20 °C	0 °C	23 °C	40 °C	50 °C	60 °C	70 °C	85 °C
SMD0805P010TS/ <i>TF</i>	0.14	0.12	0.11	0.10	0.08	0.07	0.06	0.05	0.03
SMD0805P020TS/ <i>TF</i>	0.28	0.25	0.23	0.20	0.17	0.14	0.12	0.10	0.07
SMD0805P035TS/ <i>TF</i>	0.47	0.44	0.39	0.35	0.30	0.27	0.24	0.20	0.14
SMD0805P050TS/ <i>TF</i>	0.68	0.62	0.55	0.50	0.40	0.37	0.33	0.29	0.23
SMD0805P075TS/ <i>TF</i>	t.b.d.	t.b.d.	t.b.d.	0.75	t.b.d.	t.b.d.	t.b.d.	t.b.d.	t.b.d.
SMD0805P100TS/ <i>TF</i>	t.b.d.	t.b.d.	t.b.d.	1.00	t.b.d.	t.b.d.	t.b.d.	t.b.d.	t.b.d.